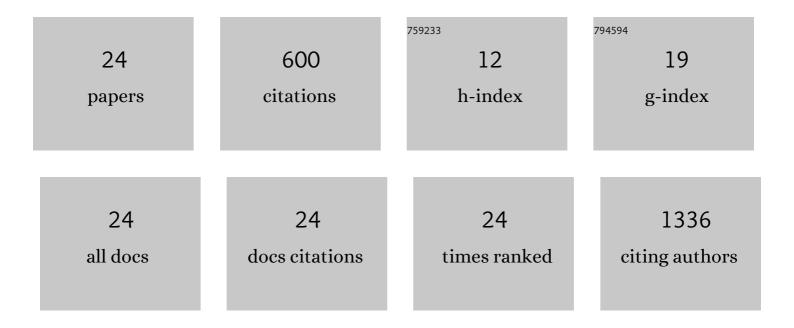
## Yuanwei Lin

List of Publications by Year in descending order

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| #  | Article   | IF   | CITATIONS |
|----|---|------|-----------|
| 1  | A universal etching-free transfer of MoS2 films for applications in photodetectors. Nano Research, 2015, 8, 3662-3672.  | 10.4 | 94        |
| 2  | Oxidativeâ€Etchingâ€Assisted Synthesis of Centimeterâ€Sized Singleâ€Crystalline Graphene. Advanced<br>Materials, 2016, 28, 3152-3158.                                       | 21.0 | 81        |
| 3  | Direct observation of single-molecule hydrogen-bond dynamics with single-bond resolution. Nature<br>Communications, 2018, 9, 807.   | 12.8 | 78        |
| 4  | An organic–inorganic hybrid perovskite logic gate for better computing. Journal of Materials<br>Chemistry C, 2015, 3, 10793-10798.  | 5.5  | 77        |
| 5  | Ultra-thin wafer technology and applications: A review. Materials Science in Semiconductor<br>Processing, 2020, 105, 104681.  | 4.0  | 48        |
| 6  | Nanocrystalline Perovskite Hybrid Photodetectors with High Performance in Almost Every Figure of<br>Merit. Advanced Functional Materials, 2018, 28, 1705589.                | 14.9 | 42        |
| 7  | Graphene–DNAzyme junctions: a platform for direct metal ion detection with ultrahigh sensitivity.<br>Chemical Science, 2015, 6, 2469-2473.                                  | 7.4  | 40        |
| 8  | Novel exciton dissociation behavior in tin-lead organohalide perovskites. Nano Energy, 2016, 27,<br>638-646.  | 16.0 | 28        |
| 9  | Revealing Charge―and Temperatureâ€Dependent Movement Dynamics and Mechanism of Individual<br>Molecular Machines. Small Methods, 2019, 3, 1900464.                           | 8.6  | 21        |
| 10 | Chemically Engineered Substrates for Patternable Growth of Two-Dimensional Chalcogenide<br>Crystals. ACS Nano, 2016, 10, 10317-10323.                                       | 14.6 | 16        |
| 11 | Deep Dry Etching of Silicon with Scallop Size Uniformly Larger than 300 nm. Silicon, 2019, 11, 651-658.   | 3.3  | 15        |
| 12 | Ultrahigh Photogain Nanoscale Hybrid Photodetectors. Small, 2015, 11, 2856-2861.  | 10.0 | 14        |
| 13 | Uniformity improvement of deep silicon cavities fabricated by plasma etching with 12-inch wafer level.<br>Journal of Micromechanics and Microengineering, 2019, 29, 105010. | 2.6  | 10        |
| 14 | The application of the scallop nanostructure in deep silicon etching. Nanotechnology, 2020, 31, 315301.   | 2.6  | 8         |
| 15 | Detection of Mercury Ion with High Sensitivity and Selectivity Using a DNA/Graphene Oxide Hybrid<br>Immobilized on Glass Slides. Biosensors, 2021, 11, 300.                 | 4.7  | 8         |
| 16 | Chemical Modification of Graphene and Its Applications. Acta Chimica Sinica, 2014, 72, 277.   | 1.4  | 8         |
| 17 | Perspective on chymotrypsin detection. New Journal of Chemistry, 2020, 44, 20921-20929.   | 2.8  | 3         |
| 18 | Transparent graphene electrodes based hybrid perovskites photodetectors with broad spectral response from UV–visible to near-infrared. Nanotechnology, 2022, 33, 085204.    | 2.6  | 3         |

Yuanwei Lin

| #  | Article  | IF  | CITATIONS |
|----|--|-----|-----------|
| 19 | Estimating the Etching Depth Limit in Deep Silicon Etching. , 2019, , .  |     | 2         |
| 20 | Highly sensitive detection for cocaine using an aptamer-modified molybdenum disulfide/gold nanoparticle microarray. New Journal of Chemistry, 2020, 44, 13466-13471.                         | 2.8 | 2         |
| 21 | Towards Tilt-Free in Plasma Etching. Journal of Micromechanics and Microengineering, 0, , .  | 2.6 | 1         |
| 22 | Towards Microstructures with Ultrahigh Aspect-Ratio and Verticality in Deep Silicon Etching. , 2020, , . $\cdot$   |     | 1         |
| 23 | Molecular Physics: Revealing Charge―and Temperatureâ€Dependent Movement Dynamics and Mechanism<br>of Individual Molecular Machines (Small Methods 12/2019). Small Methods, 2019, 3, 1970041. | 8.6 | Ο         |
| 24 | A Segmented Plasma Etching Method for 2.5D/3D Through Silicon Vias. , 2021, , .  |     | 0         |